

### FEATURES

- Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- Metal silicon junction ,majority carrier conduction
- Guard ring for overvoltage protection
- Low power loss ,high efficiency
- High current capability ,low forward voltage drop
- High surge capability
- High temperature soldering guaranteed:260°C/10 seconds at terminals
- Component in accordance to RoHS 2015/863/EU
- AEC-Q101 qualified and PPAP capable



AEC-Q101 Qualified

### MECHANICAL DATA

- Case: JEDEC SMC(DO-214AB) molded plastic body
- Terminals: solder plated ,solderable per MIL-STD-750,method 2026
- Polarity: color band denotes cathode end
- Weight: 0.007ounce,0.21 gram

SMC(DO-214AB)



Marking:

JF:Logo  
xxxx:Date code  
SS810C-V:Type

### TYPICAL APPLICATIONS

For use in low voltage,high frequency inverter,DC/DC converters,  
free wheeling,and polarity protection applications

### MAXIMUM RATINGS

(Ratings at 25°C ambient temperature unless otherwise)

Parameter	Symbol	Value	Unit
Maximum repetitive peak reverse voltage	$V_{RRM}$	100	V
Maximum average forward rectified current	$I_F(AV)$	8.0	A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC method at rated TL)	$I_{FSM}$	150	A
Operating junction temperature range	$T_J$	-55 to +150	°C
Storage temperature range	$T_{stg}$	-55 to +150	°C

## RATINGS AND CHARACTERISTICS OF SS810C-V

### ELECTRICAL CHARACTERISTICS (T<sub>A</sub>=25°C Unless otherwise noted)

Parameter	Test Conditions		Symbol	Typ.	Max.	Unit
Instaneous Forward Voltage	T <sub>J</sub> =25°C	I <sub>F</sub> =1A	V <sub>F</sub> <sup>1)</sup>	0.52	-	V
		I <sub>F</sub> =3A		0.63	-	
		I <sub>F</sub> =8A		0.75	0.82	
	T <sub>J</sub> =125°C	I <sub>F</sub> =1A		0.40		
		I <sub>F</sub> =3A		0.51	-	
		I <sub>F</sub> =8A		0.59	-	
Reverse Current	T <sub>J</sub> =25°C	V <sub>R</sub> =100V	I <sub>R</sub> <sup>2)</sup>	-	5.0	μA
	T <sub>J</sub> =125°C			-	5.0	mA
Typical Junction Capacitance	4V, 1MHz		C <sub>J</sub>	234		pF

Notes: 1.Pulse test: 300 μs pulse width, 1% duty cycle

2.Pulse test: pulse width ≤ 40ms

### THERMAL CHARACTERISTICS

Parameter	Symbol	SMC	Unit
Typical thermal resistance <sup>3)</sup>	R <sub>θJA</sub>	55.0	°C/W
	R <sub>θJL</sub>	17.0	

3.P.C.B. mounted with 0.55" x 0.55" (14.0 mm x 14.0 mm) copper pad areas

### AVAILABLE PACK INFORMATION

Product code	Pack	Reel Size (mm)	Quantity (pcs/reel)	Box Size L×W×H (mm)	Quantity (reel/box)	Carton Size L×W×H (mm)	Quantity (box/carton)	Quantity (carton)
SS810C-SMC	T/R	Φ330	3000	338×338×39	2	370×370×360	8	48

Fig.1-Forward Current Derating Curve

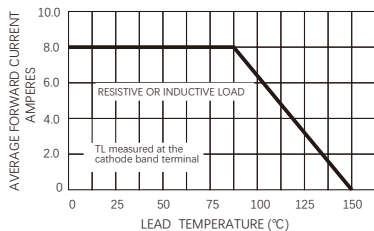


Fig.2-maximum Non-repetitive Peak Forward Surge Current

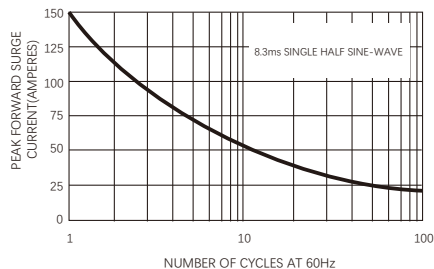


Fig.3-Typical Instantaneous Forward Characteristics

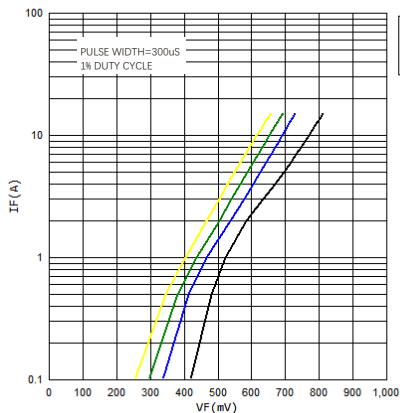


Fig.4-Typical Reverse Characteristics

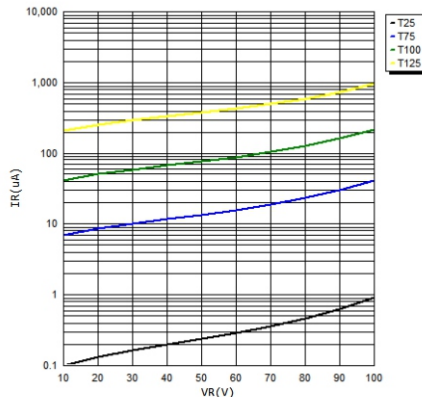
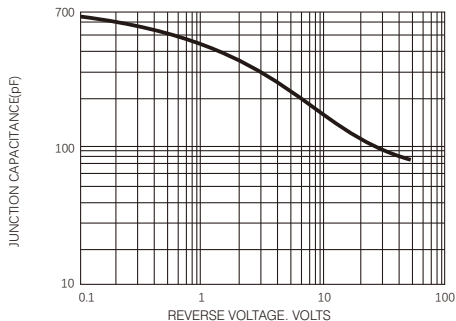
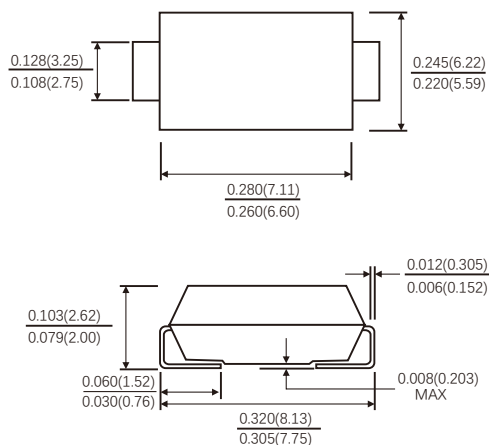


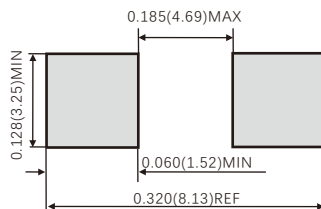
Fig.5-Typical Junction Capacitance



## SMC(DO-214AB)



## Suggested PAD Layout



Dimensions in inches and (millimeters)

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